

1. Electrical Specification

1-1 Test condition

Varistor voltage	$I_n = 1 \text{ mA DC}$
Leakage current	$V_{dc} = 5.0 \text{ V DC}$
Maximum clamping voltage	$I_c = 1 \text{ A}$
Rated peak single pulse transient current	8 / 20 μs waveform, +/- each 1 time induce
Capacitance	10/1000 μs waveform
Insulation resistance after reflow soldering	$f = 1 \text{ MHz}$, $V_{rms} = 0.5 \text{ V}$
Reflow soldering condition	Soldering paste : Tamura (Japan) RMA-20-21L
	Stencil : SUS, 120 μm thickness
	Pad size : 0.5 (Width) x 0.6 (Length)
	0.5 (Distance between pads)
	Soldering profile : $260 \pm 5 \text{ }^\circ\text{C}$, 5 sec.

1-2 Electrical specification

Maximum allowable continuous DC voltage	5.0	V	
trigger voltage / Varistor voltage / breakdown voltage	100-150	V	
Maximum clamping voltage	200	V	Maximum
Rated peak single pulse transient current	1	A	Maximum
Nonlinearity coefficient	> 12		
Leakage current at continuous DC voltage	< 0.1	μA	
Response time	< 0.5	ns	
Varistor voltage temperature coefficient	< 0.05	%/ $^\circ\text{C}$	
Capacitance measured at 1MHz	0.8	pF	Typical
Capacitance tolerance	-50 to +50	%	
Insulation resistance after reflow soldering on PCB	> 10	$\text{M}\Omega$	
Operating ambient temperature	-55 to +85	$^\circ\text{C}$	
Storage temperature	-55 to +125	$^\circ\text{C}$	

1-3 Reliability testing procedures

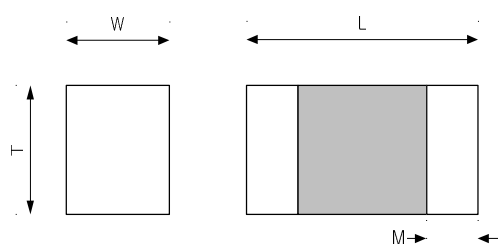
Reliability parameter	Test	Test methods and remarks	Test requirement
Pulse current capability	I _{max} 8/20 μ s	IEC 1051-1, Test 4.5. 10 pulses in the same direction at 2 pulses per minute at maximum peak current	$d V_n / V_n \leq 10\%$ no visible damage
Electrostatic discharge capability	ESD C=150 pF, R=330 Ω	IEC 1000-4-2 Each 10 times in positive/negative direction in 10 sec at 8KV contact discharge (Level 4)	$d V_n / V_n \leq 10\%$ no visible damage
Environmental reliability	Thermal shock	IEC 68-2-14 Condition for 1 cycle Step 1 : Min. -40°C , 30 ± 3 min. Step 2 : Max. $+125^{\circ}\text{C}$, 30 ± 3 min. Number of cycles: 30 times	$d V_n / V_n \leq 5\%$ no visible damage
	Low temperature	IEC 68-2-1 Place the chip at $-40 \pm 5^{\circ}\text{C}$ for 1000 ± 12 hrs. Remove and place for 24 ± 2 hrs at room temp. condition, then measure	$d V_n / V_n \leq 5\%$ no visible damage
	High temperature	IEC 68-2-2 Place the chip at $125 \pm 5^{\circ}\text{C}$ for 1000 ± 24 hrs. Remove and place for 24 ± 2 hrs at room temp. condition, then measure	$d V_n / V_n \leq 5\%$ no visible damage
	Heat resistance	IEC 68-2-3 Apply the rated voltage for 1000 ± 48 hrs at $85 \pm 3^{\circ}\text{C}$. Remove and place for 24 ± 2 hrs at room temp. condition, then measure	$d V_n / V_n \leq 5\%$ no visible damage
	Humidity resistance	IEC 68-2-30 Place the chip at $40 \pm 2^{\circ}\text{C}$ and 90 to 95% humidity for 1000 ± 24 hrs. Remove and place for 24 ± 2 hrs at room temp. condition, then measure	$d V_n / V_n \leq 10\%$ no visible damage
	Pressure cooker test	Place the chip at 2 atm, 120°C , 85%RH for 60 hrs. Remove and place for 24 ± 2 hrs at room temp. condition, then measure	$d V_n / V_n \leq 10\%$ no visible damage
	Operating life	Apply the rated voltage for 1000 ± 48 hrs at $125 \pm 3^{\circ}\text{C}$. Remove and place for 24 ± 2 hrs at room temp. condition, then measure	$d V_n / V_n \leq 10\%$ no visible damage

Mechanical Reliability	Solderability	<u>IEC 68-2-58</u> Solder bath method, $230 \pm 5^{\circ}\text{C}$, 2s	At least 95% of terminal electrode is covered by new solder
	Resistance to soldering heat	<u>IEC 68-2-58</u> Solder bath method, $260 \pm 5^{\circ}\text{C}$, $10 \pm 0.5\text{s}$, $270 \pm 5^{\circ}\text{C}$, $3 \pm 0.5\text{s}$	$d V_n / V_n \leq 5\%$ no visible damage
	Bending strength	<u>IEC 68-2-21</u> Warp:2mm, Speed:0.5mm/sec, Duration: 10sec. The measurement shall be made with board in the bent position	$d V_n / V_n \leq 5\%$ no visible damage
	Adhesive strength	<u>IEC 68-2-22</u> Applied force on SMD chip by fracture from PCB	Strength>10 N no visible damage

2. Material Specification

Body	ZnO based ceramics
Internal electrode	Silver – Palladium
External electrode	Silver – Nickel – Tin
Thickness of Ni/Sn plating layer	Nickel > 1 μm , Tin > 2 μm

3. Dimension Specification

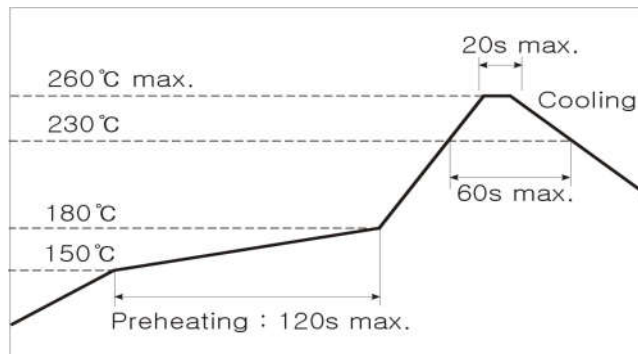


Size	L(mm)	W(mm)	T(mm)	M(mm)
0201	0.6 ± 0.03	0.3 ± 0.03	≤ 0.3	0.15 ± 0.05
0402	1.0 ± 0.10	0.5 ± 0.10	≤ 0.6	0.20 ± 0.10

4. Soldering Recommendations

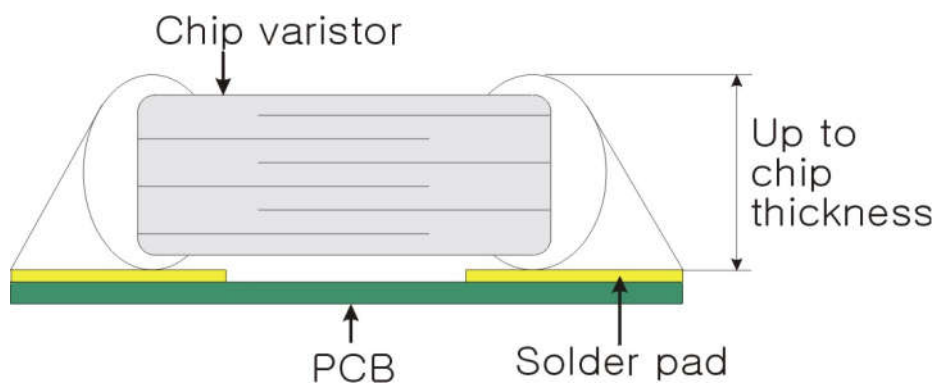
4-1 Soldering profile

4-1-1 Pb free solder paste



4-1-2 Repair soldering

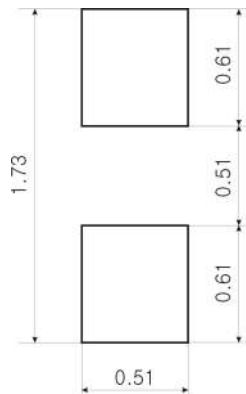
- Allowable time and temperature for making correction with a soldering iron : 350 ± 10 °C, 3 sec.
- Optimum solder amount when corrections are made using a soldering iron



4-2 Soldering guidelines

- Our chip varistors are designed for reflow soldering only. Do not use flow soldering
- Use non-activated flux (Cl content 0.2% max.)
- Follow the recommended soldering conditions to avoid varistor damage.

4-3 Solder pad layout



5. Storage condition

- Storage environment must be at an ambient temperature of 25~35 °C and an ambient humidity of 40~60 % RH
- Chip varistors can experience degradation of termination solderability when subjected to high temperature of humidity, or if exposed to sulfur or chlorine gases.
- Avoid mechanical shock (ex. Falling) to the chip varistor to prevent mechanical cracking inside of the ceramic dielectric due to its own weight.
- Use chips within 6 months.
If 6 months of more have elapsed, check solderability before use.-

6. Description about package label

Qunatity : 10,000 pcs

- Quantity of shipping chip varistor